



## Dual N -Channel Enhancement Power MOSFET

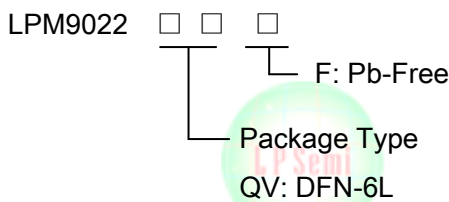
### General Description

The LPM9024 integrates two N-Channel enhancement MOSFET Transistor. It uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for using in DC-DC conversion, power switch and charging circuit. Standard Product LPM9024 is Pb-free and Halogen-free.

### Features

- ◆ Trench Technology
- ◆ Single NMOS:  $V_{DS}=20V$   
 $R_{DS(ON)} < 40m\Omega @ V_{GS}=2.5V, I_D=5A$   
 $R_{DS(ON)} < 30m\Omega @ V_{GS}=4.5V, I_D=5A$
- ◆ Super high density cell design
- ◆ Extremely Low Threshold Voltage
- ◆ Small package DFN-6L 2\*2mm

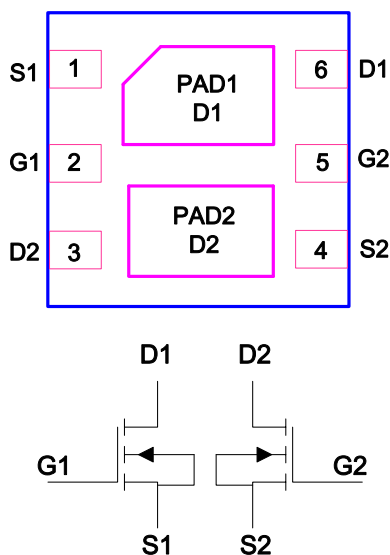
### Order Information



### Applications

- ◇ Driver for Relay, Solenoid, Motor, LED etc.
- ◇ DC-DC converter circuit
- ◇ Power Switch
- ◇ Load Switch
- ◇ Charging

### Pin Configurations



### Marking Information

Device	Marking	Package	Shipping
LPM9024		DFN-6L	3K/REEL

### Pin Description

Pin Number	Pin Description
1	Source Of NMOS1
2	Gate Of NMOS1
3/PAD2	Drain Of NMOS2
4	Source Of NMOS2
5	Gate Of NMOS2
6/PAD1	Drain Of NMOS1



## Absolute Maximum Ratings

Parameter	Symbol	LPM9022	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	
Continuous Drain Current	TA=25°C	5	A
Maximum Power Dissipation	TA=25°C	1.2	W
Operating Junction Temperature	$T_J$	-40 to 150	°C
Lead Temperature	$T_L$	260	°C
Storage Temperature Range	$T_{stg}$	-55 to 150	°C

## Thermal resistance ratings

Parameter	Symbol	LPM9022	Unit
Junction-to-Ambient Thermal Resistance	$R_{\theta JA}$	95	°C/W





## Electrical Characteristics

Parameter	Symbol	Test Condition	Min	Typ.	Max	Units
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$		20		V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20V, V_{GS} = 0V$			500	nA
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 10V$			$\pm 100$	nA
<b>ON CHARACTERISTICS ( Note c )</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	0.4		0.95	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = 2.5V, I_D = 4A$			40	m $\Omega$
		$V_{GS} = 4.5V, I_D = 5A$			30	
Forward Transconductance	$g_{FS}$	$V_{DS} = 2.5V, I_D = 6A$	4			S
<b>CAPACITANCES, CHARGES ( Note d )</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0V,$ $f = 1.0MHz$ $V_{DS} = 15V$		1550		pF
Output Capacitance	$C_{OSS}$			300		
Reverse Transfer Capacitance	$C_{RSS}$			180		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5V,$ $V_{DS} = 15V,$ $I_D = 10A$		13		nC
Gate-to-Source Charge	$Q_{GS}$			5.5		
Gate-to-Drain Charge	$Q_{GD}$			3.5		
<b>SWITCHING CHARACTERISTICS ( Note d )</b>						
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 10V,$ $V_{DD} = 20V,$ $I_D = 1.0A,$ $R_G = 6\Omega$		30		ns
Rise Time	$t_r$			20		
Turn-Off Delay Time	$t_{d(OFF)}$			100		
Fall Time	$t_f$			80		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage( Note c )	$V_{SD}$	$V_{GS} = 0V, I_S = 1A$		0.2	1.0	V

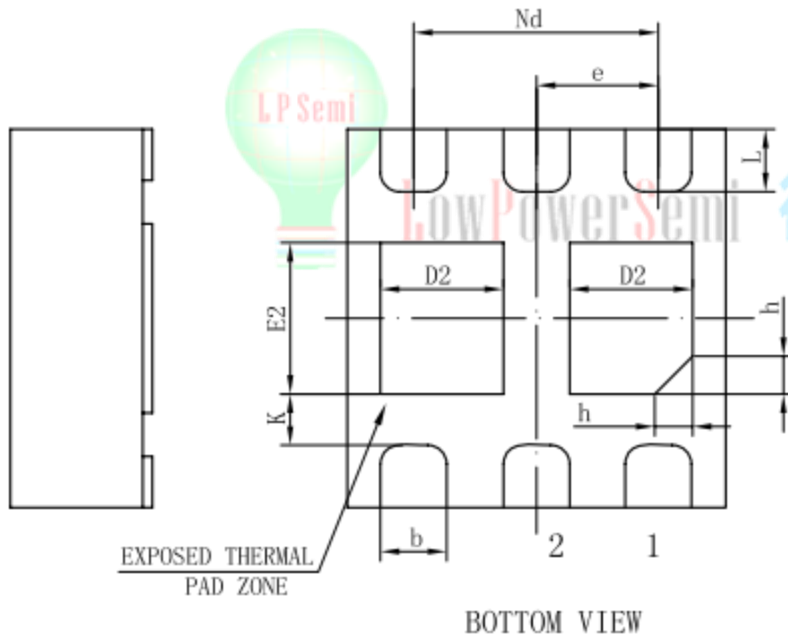
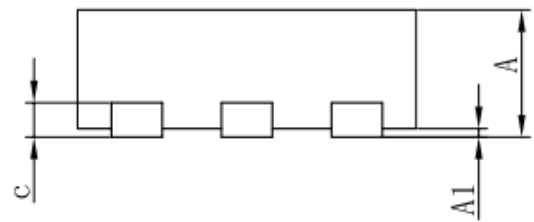
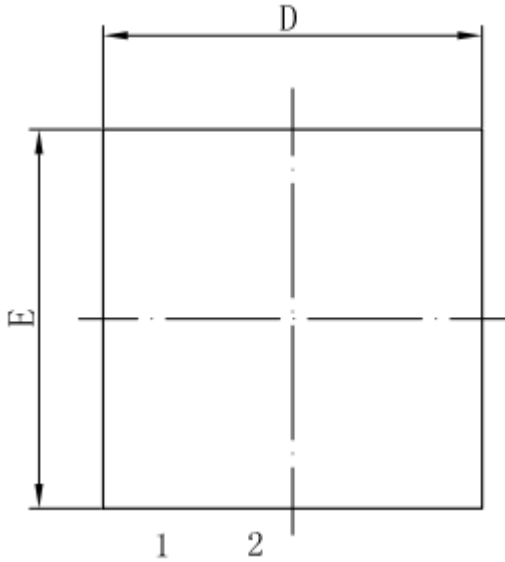
**Note:**

- a. Pulse width limited by maximum junction temperature.
- b. Surface mounted on FR4 board,  $t < 10s$ .
- c. Pulse width  $< 295\mu s$ , Duty Cycle  $< 2\%$ .
- d. Guaranteed by design, not subject to production.



## Packaging Information

DFN-6L



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0	0.02	0.05
b	0.30	0.35	0.40
c	0.18	0.20	0.25
D	1.95	2.00	2.05
D2	0.60	0.65	0.70
e	0.65BSC		
Nd	1.30BSC		
E	1.95	2.00	2.05
E2	0.75	0.80	0.85
K	0.20	-	-
L	0.28	0.33	0.38
h	0.15	0.20	0.25